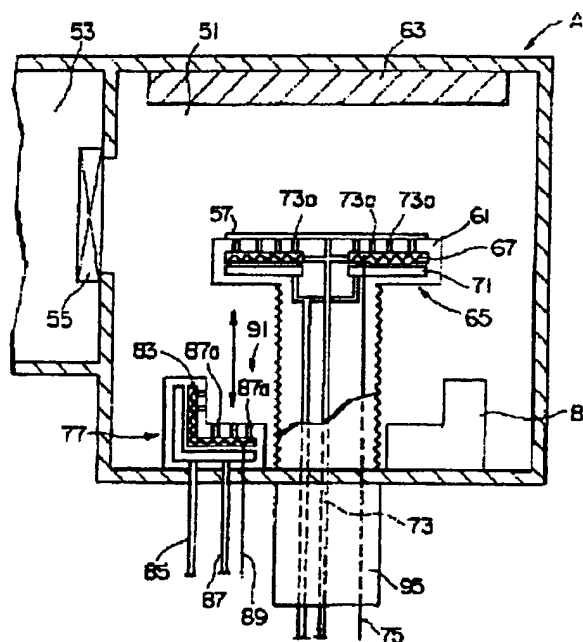


# EUROPEAN PATENT OFFICE

## Patent Abstracts of Japan

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APPLICANT : NEC CORP;  
  
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TITLE : SPUTTERING DEVICE



**ABSTRACT :** **PROBLEM TO BE SOLVED:** To provide a sputtering device equipped with a heating/cooling mechanism which is capable of shortening a holder temperature switching time and stably keeping a substrate holder at a set temperature in each process carried out under different conditions in a sputtering process where a first processing condition is changed to a second processing condition.

**SOLUTION:** An auxiliary block 81 where a second heating/cooling mechanism 77 used for heating/cooling a substrate holder 61 is built in is provided under a substrate holder 61 surrounding it inside a sputtering chamber 51. A heating gas pipe 87 is provided as the second heating/cooling mechanism 77 to the auxiliary block 81, and heat is transferred between the auxiliary block 81 and the substrate holder 61 through the intermediary of gas as heat transfer medium.

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